APPLIC <i>A</i>	ABLE STAN	IDARD										
OPERATING TEMPERATUR		RE RANGE	-35°C TO +85°C(NO	OTE 1)		ERATU	RE RANGE		-10°C TO +60°C(I	NOTE	3)	
RATING	OPERATING HUMIDITY RANGE		40 % TO 80 % (NC	TE 2)	STOR/ HUMIC		AGE DITY RANGE		40 % TO 70 %(N	OTE:	3)	
CURRENT		-	1 A/pin		VOL	TAGE	AGE		150 V AC (DC)			
	APPLICABLE CONNECTOR		DE14-"S-1750			PLICABLE DF14			DF14-***S	4-***SCF		
	CONNECTOR		SPEC	IFICA								
1-	ТЕМ		TEST METHOD		1.0.	•••	RF(	) IIR	REMENTS	QT	АТ	
	RUCTION	1	TEOT METHOD				IVE	QUIIV	CEMERTO	Q I	71	
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.				ACCORDING TO DRAWING.					X	
MARKING		CONFIRMED VISUALLY.				-				X		
FI FCTR	IC CHARA	CTERI	STICS								1 /	
	RESISTANCE	20 mV MAX, 1mA (DC OR 1000 Hz)				30 mΩ MAX.					Τ_	
INSULATION		100 V DC.			5	500 MΩ MIN.						
RESISTANCE										Х	_	
VOLTAGE PROOF		500 V AC FOR 1 min.			N	NO FLASHOVER OR BREAKDOWN.					_	
MECHA	VICAL CHA											
MECHANICAL OPERATION		30 TIMES INSERTIONS AND EXTRACTIONS.				1) CONTACT RESISTANCE: 30 mΩ MAX. 2) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.					-	
VIBRATION		0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			2	1) NO ELECTRICAL DISCONTINUITY OF 1µs. 2) NO DAMAGE, CRACK OR LOOSENESS OF					-	
SHOCK		490 m/s <sup>2</sup> DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.				PARTS.						
			ACTERISTICS				T. 07 DE0	0711	105.00.0141	1	1	
RAPID CHANGE OF TEMPERATURE		TIME $30 \rightarrow 10 \text{ TO } 15 \rightarrow 30 \rightarrow 10 \text{ TO } 15 \text{ min.}$ UNDER 5 CYCLES.			5 min. 2	1) CONTACT RESISTANCE: 30 mΩ MAX. 2) INSULATION RESISTANCE: 500 MΩ MIN. 3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.					-	
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.										
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING  «REFLOW AREA»  MAX 250°C WITHIN 10 sec  MIN 230°C WITHIN 60 sec  «PREHEATING AREA»  170°C to 190°C 60 sec To 120 sec  PUT THROUGH IN REFLOW FUMACE TWICE.  LEAVE IN AMBIENT TEMPERATURE AND  HUMIDITY FOR 1 HOUR.  CONNECTOR TEMPERTURE TO BE  AMBIENT FOR SECOND REFLOW.  2) MANUAL SOLDERING  SOLDERING IRON TEMPERATURE  350±5°C, FOR 5±1 sec.  NO STRENGTH ON CONTACT.			1	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.						
SOLDERABILITY		SOLDERING TEMPERATURE : 245±5°C DURATION OF IMMERSION :				A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE						
NOTE2: NO ( NOTE3: APPI	CONDENSING LY TO THE CON	SOLDER MPERATUR IDITION OF	ING, FOR 3 sec.  RE RISE BY CURRENT.  LONG TERM STORAGE FOR LING TEMPERATURE AND HUMID		RODUCTS	SURFA S BEFC	CE BEING  DRE MOUNT	ED O	ERSED.  ON PCB.	X		
COUN	IT DE	SCRIPTION	ON OF REVISIONS		DESIGN				CHECKED	D	ATE	
Δ												
Unless ot	herwise spe	cified, re	cified, refer to IEC 60512.			APPROVED CHECKED		D	HS.OKAWA			
								D	TS.KUMAZAWA			
							DESIGNE	D	HK.HAYASHI	202	00316	
						DRAWN			DS.HIROWATARI 202		00311	
Note QT:0	Qualification Te	est AT:As	surance Test X:Applicable Test D		DR	RAWING NO.			ELC-160307-35-00			
H25			O/THON OHEET		PART I	NO.		DF14-*P-1.25H(35)				
HIR		OSE E	OSE ELECTRIC CO., LTD.		CODE NO.			CL538 🔼				